



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN#20251017001.1**  
**Qualification of RFAB as an additional Fab site,**  
**Die Revision and CDAT as additional**  
**Assembly site option for select devices**  
**Change Notification / Sample Request**

**Date:** October 17, 2025

**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team  
SC Business Services

**20251017001.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
SN74LVC541ARGYR	SN74LVC541ARGYR
SN74LVC244ARGYR	NULL
SN74LVC541ARGYRG4	SN74LVC541ARGYR

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20251017001.1		<b>PCN Date:</b>	October 17, 2025																			
<b>Title:</b>	Qualification of RFAB as an additional Fab site, Die Revision and CDAT as additional Assembly site option for select devices																						
<b>Customer Contact:</b>	Change Management Team		<b>Dept:</b>	Quality Services																			
<b>Proposed 1<sup>st</sup> Ship Date:</b>	January 15, 2026		<b>Sample requests accepted until:</b>	December 16, 2025*																			
*Sample requests received after December 16, 2025 will not be supported.																							
<b>Change Type:</b>																							
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material																		
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process																		
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site																		
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material																		
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process																		
<b>PCN Details</b>																							
<b>Description of Change:</b>																							
Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option for the devices listed below.																							
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>FFAB</td> <td>ASLC10</td> <td>200mm</td> <td>RFAB</td> <td>LBC9</td> <td>300mm</td> </tr> </tbody> </table>						Current Fab Site			Additional Fab site			Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter	FFAB	ASLC10	200mm	RFAB	LBC9	300mm
Current Fab Site			Additional Fab site																				
Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter																		
FFAB	ASLC10	200mm	RFAB	LBC9	300mm																		
The die was also changed as a result of the process change.																							
Construction differences as follows:																							
<table border="1"> <thead> <tr> <th></th> <th>Current site</th> <th>Additional site</th> </tr> </thead> <tbody> <tr> <td>Assembly site</td> <td>MLA</td> <td>CDAT</td> </tr> <tr> <td>Wire diam/type</td> <td>0.96mil Cu</td> <td>0.80mil Cu</td> </tr> <tr> <td>Mount compound</td> <td>4205846</td> <td>4207123</td> </tr> <tr> <td>Mold compound</td> <td>4208625</td> <td>4222198</td> </tr> </tbody> </table>							Current site	Additional site	Assembly site	MLA	CDAT	Wire diam/type	0.96mil Cu	0.80mil Cu	Mount compound	4205846	4207123	Mold compound	4208625	4222198			
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Assembly site	MLA	CDAT																					
Wire diam/type	0.96mil Cu	0.80mil Cu																					
Mount compound	4205846	4207123																					
Mold compound	4208625	4222198																					
Qual details are provided in the Qual Data Section.																							
<b>Reason for Change:</b>																							
Supply Continuity																							
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>																							
None																							
<b>Impact on Environmental Ratings</b>																							
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																							
<b>RoHS</b>		<b>REACH</b>		<b>Green Status</b>																			
<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change		<input checked="" type="checkbox"/> No Change																			
				<b>IEC 62474</b>																			
				<input checked="" type="checkbox"/> No Change																			
<b>Changes to product identification resulting from this PCN:</b>																							
<b>Fab Site Information:</b>																							
Chip Site	Chip Site Origin	Chip Site Country	Chip Site City																				

	Code (20L)	Code (21L)	
FFAB	TID	DEU	Freising
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>


**Die Rev:**
**Current**
**New**

Die Rev [2P]	<b>Die Rev [2P]</b>
-	<b>A</b>

**Assembly Site Information:**

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TI Malaysia	MLA	MYS	Kuala Lumpur
<b>TI Chengdu</b>	<b>CDA</b>	<b>CHN</b>	<b>Chengdu</b>

Sample product shipping label (not actual product label):

 **TEXAS INSTRUMENTS**  
 MADE IN: Malaysia  
 2DC: 2d:  
 MSL 2 /260C/1 YEAR SEAL DT  
 MSL 1 /235C/UNLIM 03/29/04  
 OPT:  
 ITEM: 39  
**LBL: 5A (L)T0:1750**



(1P) **SN74LS07NSR**  
 (Q) **2000** (D) **0336**  
 (31T) LOT: 3959047MLA  
 (4W) TKY (1T) 7523483S12  
 (P)  
 (2P) REV: (V) **0000017**  
 (20L) CS0: SHE (21L) CC0:USA  
 (22L) AS0: MLA (23L) AC0: MYS

**Product Affected:**

SN74LVC244ARGYR	SN74LVC541ARGYR
SN74LVC244ARGYRG4	SN74LVC541ARGYRG4

# Qualification Report

Approve Date 15-July -2025

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">SN74LVC244ARGYR</a>	Qual Device: <a href="#">SN74LVC541ARGYR</a>	Process QBS Reference: <a href="#">SN74HCS740PWR01</a>	Package QBS Reference: <a href="#">TS3A5017QRGYR01</a>	Product QBS Reference: <a href="#">SN74LVC244AWRKS01</a>	Product QBS Reference: <a href="#">SN74LVC7541APWR01</a>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74LVC244ARGYR is qualified at MSL2 260C

Qual Device SN74LVC541ARGYR is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2503-034

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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